

Attorney Docket No. 108298744US
Micron Docket No. 2003-0477.00/US

Used in Lieu of PTO/SB/08A/B
(Based on PTO 01-08 version)

Substitute for form 1449/PTO			Complete if Known		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)			Application Number	10/733,226-Conf. #8010	
			Filing Date	December 10, 2003	
			First Named Inventor	William M. Hiatt	
			Art Unit	2811	
			Examiner Name	C. A. Matthews	
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Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (#/known)			
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				Application Number	10/733,226-Conf. #8010
				Filing Date	December 10, 2003
				First Named Inventor	William M. Hiatt
				Art Unit	2811
				Examiner Name	C. A. Matthews
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			Art Unit	2811	
			Examiner Name	C. A. Matthews	
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